



Material Content Data Sheet



Halogen-Free

Sales Product Name	DHP0050N10N5	Issued	11. August 2021
MA#	MA005405717		
Package	PG-IQFN-36-1	Weight*	153.27 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.355	0.88	0.88	8840	8840
chip_2	inorganic material	silicon	7440-21-3	1.334	0.87	0.87	8702	8702
chip_3	inorganic material	silicon	7440-21-3	1.387	0.90	0.90	9047	9047
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		105	
	non noble metal	zinc	7440-66-6	0.065	0.04		421	
	non noble metal	iron	7439-89-6	1.291	0.84		8424	
	non noble metal	copper	7440-50-8	52.428	34.21	35.10	342061	351011
wire	noble metal	gold	7440-57-5	0.295	0.19	0.19	1927	1927
encapsulation	organic material	carbon black	1333-86-4	0.120	0.08		786	
	plastics	epoxy resin	-	6.205	4.05		40481	
	inorganic material	silicondioxide	60676-86-0	53.913	35.18	39.31	351754	393021
leadfinish	non noble metal	tin	7440-31-5	1.904	1.24	1.24	12421	12421
plating	noble metal	silver	7440-22-4	0.763	0.50	0.50	4980	4980
solder	noble metal	silver	7440-22-4	0.142	0.09		923	
	non noble metal	tin	7440-31-5	0.283	0.18		1847	
	non noble metal	lead	7439-92-1	5.237	3.42	3.69	34168	36938
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008	0.01		52	
	non noble metal	zinc	7440-66-6	0.032	0.02		208	
	non noble metal	iron	7439-89-6	0.637	0.42		4155	
	non noble metal	copper	7440-50-8	25.856	16.87	17.32	168698	173113
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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